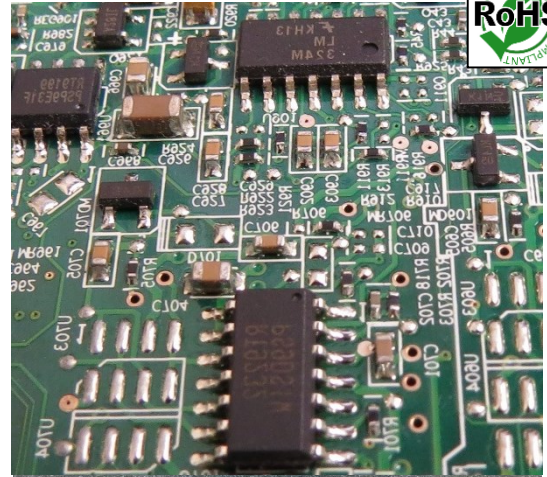




MesoGlue Metallic Glues

MesoGlue is a revolutionary joining solution that allows the attachment of items together with a metal bond. It is similar to welding or soldering, but requires lower temperatures (room temperature in some cases). The patented process gives the strength and thermal/electrical conductance of a metal bond, with the ease of attachment of glue. Surfaces are merely pressed together to form a very strong connection.



Features

- High Thermal Conductivity
- High Electrical Conductivity
- High Mechanical Strength
- Stable to High Temperature when Cured (>500°C)

Applications

- Thermal Interface Materials
- Soldering
- Attachment of Different CTE Materials
- 3D Printing

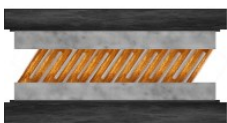
The Technology: Phase 1

- High purity process allows for best interface properties and thinnest bonds.
- Requires use of a high vacuum chamber.



MesoGlue Silver:

A pure silver bond offering the highest electrical and thermal conductivity. Formation of the bond requires moderate pressure (100-1000psi) or temperature (20-100°C).



MesoGlue Eutectic:

A bond made of primarily copper with other metals added to help the sealing. Formation of the bond requires only light pressure (<100psi.)

The Technology: Phase 2

- Inexpensive and simple solution. No vacuum required.



MesoGlue GlueGun:

A liquid metal glue is produced by our simple to use MesoGlue Gun. It sets in minutes and is temperature stable to over 500°C. Excellent for less precise applications: soldering, 3D printing, etc.